

PREFACE

Dear Distinguished Delegates and Guests,

The 4th International Conference on Computer-Aided Design, Manufacturing, Modeling and Simulation (CDMMS2014) was held in Chongqing, China, from September 13-15, 2014, serving as a platform for expertise exchange. CDMMS2014 had drawn the attention of researchers from various disciplines: CAD, CAM, Manufacturing, Mechanical Engineering, Modeling and simulation, etc.

Persons who attended the conference were engineers, scientists, managers of various companies and professors of the universities abroad and home. We have had record number of submission 746 this year. From which 229 papers have been accepted for presentation at the conference and will be published by TTP, in Applied Mechanics and Materials (AMM) Journal (ISSN: 1660-9336), which is online available in full text via the platform www.scientific.net. AMM should be indexed by EI according the previous TTP index results.

We express our special gratitude to all the members of the General Committee Chairs, Program Committee Chairs, Technical Program Committee and Steering Committee who worked so hard to prepare the conference and who supported the conference so professionally.

The 4th International Conference on Computer-Aided Design, Manufacturing, Modeling and Simulation (CDMMS2014) is organized by Hunan Institute of Engineering, Zhejiang Gongshang University, Nanyang Technological University, Shanghai Jiao Tong University, and sponsored by National Natural Science Foundation of China (NSFC). Their kind support makes CDMMS2014 become possible. Especially, we should thank the TTP.

Finally, we would like to thanks all the authors, speakers and participants of this conference for taking part in and contributing to the International Conference on Computer-Aided Design, Manufacturing, Modeling and Simulation.

We hope you have a unique, rewarding and enjoyable week at CDMMS2014 in Chongqing, China.

With our warmest regards,

CDMMS2014 Organizing Committees
September 13-15, 2014
Chongqing, China

COMMITTEES

Conference Chairs

M. Ma, Nanyang Technological University, Singapore

X. Qu, Hunan Institute of Engineering, China

Program Committee Chairs

Y. Yang, Shanghai Jiao Tong University, China

M. Gao, National Institute of AIST, Japan

Organizing Chair

K. Wei, Hunan Institute of Engineering, China

J. Chen, University of Vigo, Spain

Publication Chairs

M. Ma, Nanyang Technological University, Singapore

A. Dou, Hunan Institute of Engineering, China

Technical Program Committee

X. Chen, Jiangsu University, China

H. Wang, Pohang University of Science and Technology, Korea

X. Wang, Hebei Polytechnic University, China

B.J. Zhang, Henan Institute of Science and Technology, China

H. Si, Nanjing University of Aeronautics and Astronautics, China

M. Cai, Zhejiang Gongshang University, China

Z. Zhou, Dongguan University of Technology, China

O. Ercetin, Sabanci University, Turkey

H. Kim, Korea University, Korea,

S. Tsai, National Chengchi University, Taiwan

Y. Li, Shanghai Jiao Tong University, China

Y. Lin, Norwegian University of Science and Technology, Norwegian

J. Chen, University of Vigo, Spain

H. Wang, University of Evry in France, France

D. Gong, Hebei Polytechnic University, China

C. Yu, Yanshan University, China

Y. Sun, Beijing University of Posts and Telecommunications, China

M. Gao, National Institute of AIST, Japan

G. Gui, CMC Corporation, China

H. Bao, Fuji Xerox Co., Ltd., Japan

X. Hu, Wuhan University of Technology, China

M. Liao, Cisco China R&D Center, China

Y. Zou, Apple China Co., Ltd., China

Y. Guo, Huazhong Normal University, China

M. Anwas, Lahore University of Management Science Lahore, Pakistan

M. Chen, Tatung University, Taiwan

K. Choi, Korea Advanced Institute of Science and Technology, Korea

D. Cui, Xi'an University of Technology, China

M. Fei, Shanghai University, China

X. Qu, Hunan Institute of Engineering, China

J. Gan, University of Essex, UK

Marko Hoevar, University of Ljubljana, Slovenia

Z. Jiang, Hiroshima Institute of Technology, Japan

M. Watts, Lincoln University, New Zealand

M. Awais, Lahore University of Management Science Lahore, Pakistan

J. Cao, Southeast University, China

W. Cao, Zhejiang University of Technology, China

M. Ma, Nanyang Technological University, Singapore

K. Wei, Hunan Institute of Engineering, China

D. Liu, Shenyang Ligong University, China

Z. Wei, Beijing Forestry University, China

H. Chen, Hu'nan University, China

REVIEWERS

J. Chen, University of Vigo, Spain
R. Tang, Ocean University of China, China
L. Shi, IBM Research Lab, China
D. Liu, ShenYang Ligong University, China
S. Hua, National Central University, Taiwan
G. Gao, Henan Institute of Science and Technology, China
G. Gui, CMC Corporation, China
M. Liao, Cisco China R&D Center, China
Y. Lin, Norwegian University of Science and Technology, Norwegian
Y. Zou, Apple China Co., Ltd., China
X. Zhang, Nanyang Normal University, China
Z. Wei, Beijing Forestry University, China
Y. Li, Shanghai Jiao Tong University, China
H. Bao, NTT Co., Ltd., Japan
X. Hu, Wuhan University of Technology, China
Z. Liu, AT&T, USA
Y. Jin, Shanghai University, China
H. Chen, Hu'nan University, China
L. Wang, Beijing University of Posts and Telecommunications, China
X. Chen, Jiangsu University, China
H. Wang, Pohang University of Science and Technology, Korea
X. Wang, Hebei Polytechnic University, China
B.J. Zhang, Henan Institute of Science and Technology, China
H. Si, Nanjing University of Aeronautics and Astronautics, China
M. Cai, Zhejiang Gongshang University, China
Z. Zhou, Dongguan University of Technology, China
O. Ercetin, Sabanci University, Turkey
H. Kim, Korea University, Korea
D. Gong, Hebei Polytechnic University, China
C. Yu, Yanshan University, China
Y. Sun, Beijing University of Posts and Telecommunications, China
M. Gao, National Institute of AIST, Japan
D. Cui, Xi'an University of Technology, China
M. Fei, Shanghai University, China
X. Qu, Hunan Institute of Engineering, China
J. Cao, Southeast University, China
W. Cao, Zhejiang University of Technology, China
Z. Wei, Beijing Forestry University, China